



**GP
ELECTRONICS**

GPEMN2012

20V N-Channel MOSFET

Product Summary

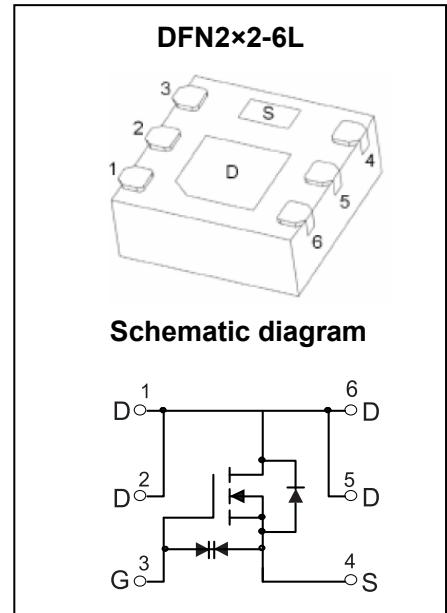
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
20V	9m Ω @4.5V	12A
	11.5m Ω @2.5V	
	20m Ω @1.8V	

Feature

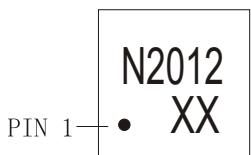
- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance

Application

- Load Switch for Portable Application



MARKING:



N2012 = Device Code

XX = Date Code

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	20	V
Gate - Source Voltage	V_{GS}	± 10	V
Continuous Drain Current ¹	I_D	12	A
Pulsed Drain Current ²	I_{DM}	40	A
Power Dissipation ⁴	P_D	2.5	W
Thermal Resistance from Junction to Ambient ⁵	$R_{\theta JA}$	50	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~+150	°C

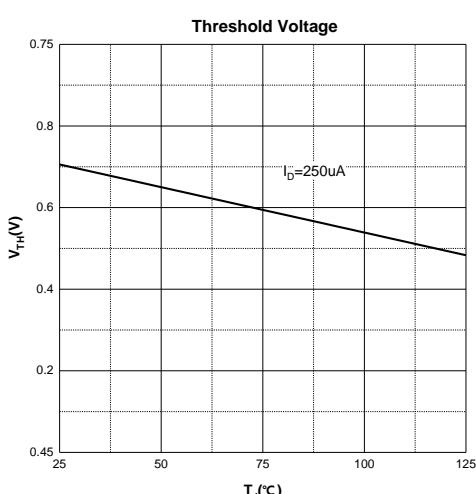
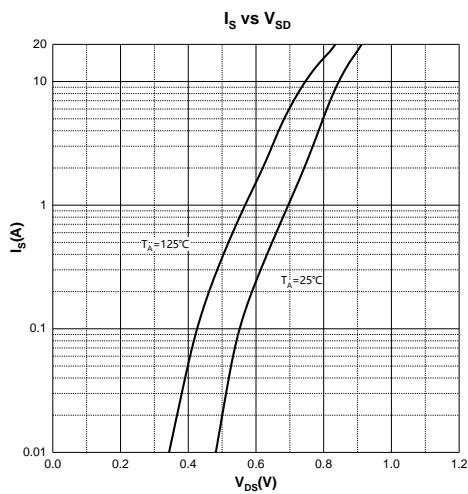
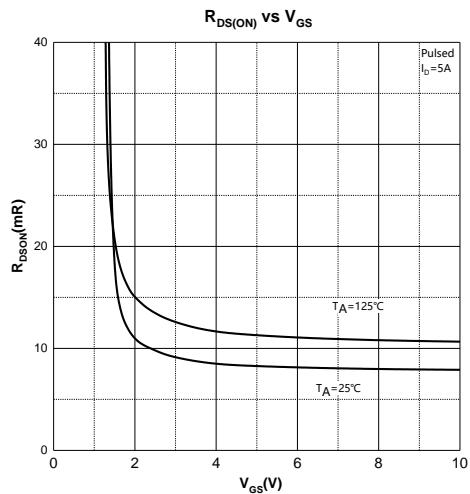
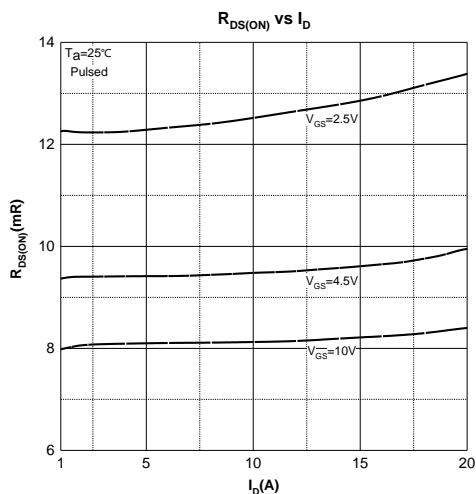
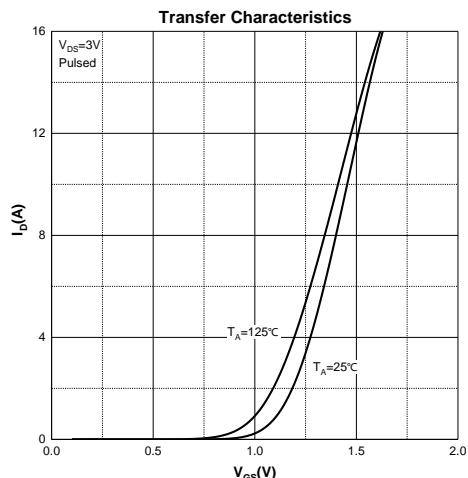
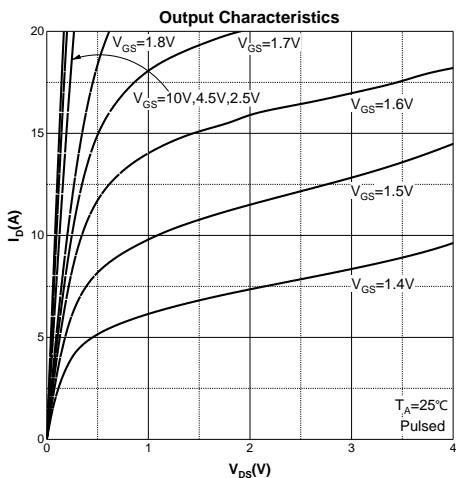
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

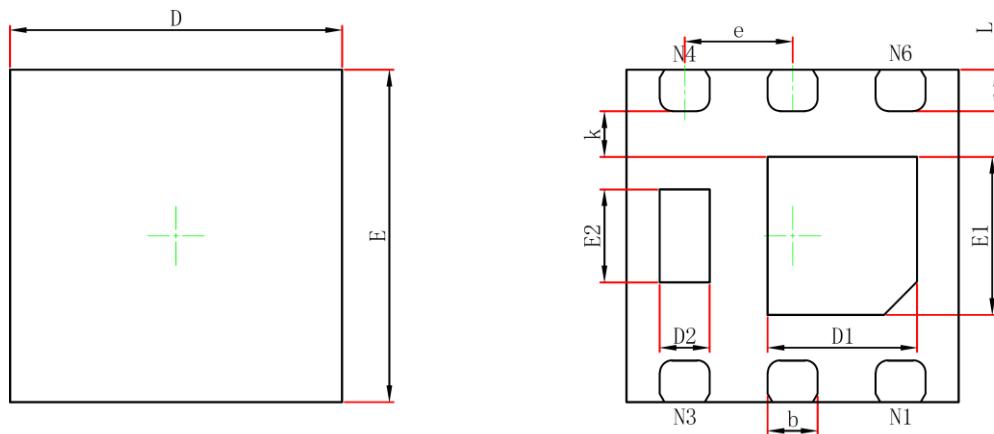
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			± 3.5	μA
On Characteristics³						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.4	0.7	1.0	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 5.0\text{A}$		9	15	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 5.0\text{A}$		11.5	18	
		$V_{\text{GS}} = 1.8\text{V}, I_D = 5.0\text{A}$		20	30	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 0\text{V}, f = 0.1\text{MHz}$		648		pF
Output Capacitance	C_{oss}			157		
Reverse Transfer Capacitance	C_{rss}			10		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 4.5\text{V}, I_D = 8\text{A}$		18		nC
Gate-source Charge	Q_{gs}			2		
Gate-drain Charge	Q_{gd}			7		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 10\text{V}, V_{\text{GS}} = 4.5\text{V}, R_L = 1.2\Omega$ $R_G = 3\Omega$		2.5		ns
Turn-on Rise Time	t_r			7.2		
Turn-off Delay Time	$t_{\text{d}(\text{off})}$			49		
Turn-off Fall Time	t_f			10.8		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 5.0\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.
- 5.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

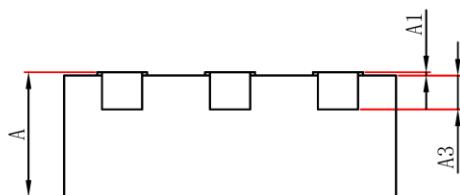
Typical Characteristics



DFN2x2-6L Package Information


TOP VIEW

BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0	0.050	0	0.002
A3	2.03REF		0.008REF	
D	1.900	2.100	0.075	0.083
E	1.900	2.100	0.075	0.083
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN		0.008MIN	
b	0.250	0.350	0.010	0.014
e	0.65BSC		0.026TYP	
L	0.174	0.326	0.007	0.013